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(54) **CIRCUIT BOARD AND CONDUCTIVE PATTERN STRUCTURE**

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(57) **ABSTRACT**

A circuit board includes a first conductive layer, a second conductive layer, and a first insulating layer disposed between the first conductive layer and the second conductive layer, wherein the first conductive layer includes a signal line, the second conductive layer includes a ground line, and the ground line of the second conductive layer includes a pattern area patterned in a meander shape.

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